L Number	Hits	Search Text	DB	Time stamp
1	19	("3870445" "5371450" "5912025" "5632222"	USPAT;	2001/07/25 13:27
		"4131596") .pn.	EPO; JPO; DERWENT; IBM TDB	
2	19	("3870445" "5371450" "5912025" "5362222" "4131596") .pn.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/25 13:28
-	164	73/856.ccls.	USPAT	2001/02/26 09:32
-	10	73/856.ccls. and mold	USPAT	2001/02/26 09:38
_	5	73/856.ccls. and (mold molding) and (injection inject pressure)	USPAT	2001/02/26 09:36
-	40553	(injection pressure) and (molding mold) and (device apparatus machine).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/26 09:42
-	9162	(injection pressure) and (molding mold) and (device apparatus machine) and (control controls).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/26 15:12
-	21	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls) and sensor and switch).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 13:34
-	. 4	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls) and (force pressure strain) near4 sensor and switch).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/26 10:00
	10	and (device apparatus machine) and (control controls) and (subtractor substractor).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/27 13:41
_	2	<pre>((injection pressure) and (molding mold) and (device apparatus machine) and (control controls)and (subtractor substractor)and (clamp clamping)).clm.</pre>	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/27 13:45
	1	<pre>((injection pressure) and (molding mold) and (device apparatus machine) and (control controls)and (subtractor substractor)and (clamp clamping)and sensor).clm.</pre>	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/02/27 13:45
-	26	("4131596" "4506321" "4714867" "5274316" "5313151" "5341452" "5362222" "5444341" "5583411").pn.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/23 17:05
_	27	("3864557" "3870445" "3878372" "3937776" "4094940" "4311446" "5232714" . "5237509").pn.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/23 17:06
_	1	((injection pressure) and (molding mold) and (device apparatus machine) and (control controls) and force near2 sensor and switch).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:01
_	1	<pre>((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls) and force near2 sensor).clm.</pre>	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:41
	1	((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls controller) and force near2 sensor).clm.	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:06
-		425/\$6.ccls. and ((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls) and force near2 sensor)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:44
-	10	425/\$6.ccls. and ((injection pressure) near2 (molding mold) near2 (device apparatus machine) and (control controls) and force near sensor)	USPAT; EPO; JPO; DERWENT; IBM TDB	2001/07/24 14:49

	·			
-	1	425/\$6.ccls. and ((injection pressure)	USPAT;	2001/07/24 14:53
		near2 (molding mold) near2 (device	EPO; JPO;	
		apparatus machine) and (control controls)	DERWENT;	1
		and force near sensor) and platen	IBM TDB	
[-	0	,, , , , ,	USPAT;	2001/07/24 14:56
		near2 (molding mold) and (control	EPO; JPO;	
		controls) and ((force near sensor) near4	DERWENT;	
		platen))	IBM TDB	
-	0	425/\$6.ccls. and ((injection pressure)	USPAT;	2001/07/24 14:56
i		near2 (molding mold) and (control	EPO; JPO;	
l		controls) and ((force near sensor) near6	DERWENT:	
		platen))	IBM TDB	
_	1	425/\$6.ccls. and ((injection pressure)	USPAT;	2001/07/24 14:57
		near2 (molding mold) and (control	EPO; JPO;	2001/01/24 14.57
		controls) and ((force near sensor) and	DERWENT;	
		platen))	IBM TDB	
l _	0		USPAT;	2001/07/24 14:58
	1	near2 (molding mold) and (clamp\$4) near2	EPO; JPO;	2001/0//24 14:58
			1	
		((force near sensor) and platen))	DERWENT;	
	,	405/06	IBM TDB	0004 407 404 44 50
_	1	425/\$6.ccls. and ((injection pressure)	USPAT;	2001/07/24 14:58
		near2 (molding mold) and (clamp\$4) and	EPO; JPO;	
		((force near sensor) and platen))	DERWENT;	
			IBM TDB	
-	0		USPAT;	2001/07/24 14:59
	:	near2 (molding mold) and (clamp\$4) near6	EPO; JPO;	
1		((force near sensor) and platen))	DERWENT;	1
İ			IBM TDB	
-	88	425/\$6.ccls. and ((injection pressure)	USPAT;	2001/07/24 14:59
		near2 (molding mold) and (clamp\$4) near6	EPO; JPO;	1
Ì		force and sensor and platen)	DERWENT:	
		* *** *	IBM TDB	
_	4	425/\$6.ccls. and ((injection pressure)	USPAT;	2001/07/24 15:06
1	_	near2 (molding mold) and (clamp\$4) near6	EPO; JPO;	=====
		force near4 sensor and platen)	DERWENT;	
		20200 Hour Follows and practing	IBM TDB	
l _	4	425/\$6.ccls. and ((injection pressure)	USPAT;	2001/07/25 13:17
] -	near2 (molding mold) and (clamp\$4 near6	EPO; JPO;	2001/07/25 13.17
		force) and (force near4 sensor) and		
			DERWENT;	
		platen)	IBM TDB	!